

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMG/17/10392	
1.3 Title of PCN	New set of material in Amkor Philippines for TSSOP14 and TSSOP16 packages	
1.4 Product Category	Selected products in TSSOP14/16	
1.5 Issue date	2017-08-23	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	FRANK WOLINSKI
2.1.2 Phone	+49 89460062287
2.1.3 Email	frank.wolinski@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Marcello SAN BIAGIO,Emanuele VAVASSORI
2.1.3 Quality Manager	Paolo MORETTI

**3. Change**

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer?)	Amkor (ATP1) Philippines

**4. Description of change**

	Old	New
4.1 Description	Molding compound = SUMITOMO EME-G700K Lead-frame = Original Matrix Lead-Frame (OMLF)	Molding compound = Sumitomo G700LS Lead-frame = High Density Lead-Frame (HDLF) or eXtreme Density Lead-Frame (XDLF)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

**5. Reason / motivation for change**

5.1 Motivation	Progressing on the activities related to quality continuous improvement, ST is glad to announce a new material set (molding compound) for TSSOP14 and TSSOP16 packages produced in Amkor Philippines. Besides, we will introduce a new lead-frame (XDLF) with higher density in order to increase our production capacity and rationalize our production tool. This change implies the phase out of the Old Lead Frame Matrix (OMLF) and High Density Lead Frame (HDLF), and it has no impact on the internal lead-frame structure.
5.2 Customer Benefit	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

6.1 Description	New finished-good codes
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**7. Timing / schedule**

7.1 Date of qualification results	2017-06-19
7.2 Intended start of delivery	2017-10-12
7.3 Qualification sample available?	Upon Request

**8. Qualification / Validation**

8.1 Description	10392 Qual Report_TSSOP14-16- f.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-08-23
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9. Attachments (additional documentations)
10392 Public product.pdf 10392 Qual Report_TSSOP14-16- f.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LM239PT	
	LM2901PT	

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